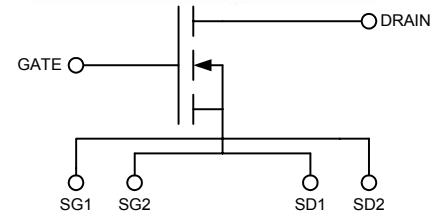


N-Channel Enhancement Mode  
 Low  $Q_g$  and  $R_g$   
 High  $dv/dt$   
 Nanosecond Switching

$V_{DSS} = 200 \text{ V}$   
 $I_{D25} = 25 \text{ A}$   
 $R_{DS(on)} = 0.08 \Omega$   
 $P_{DC} = 590 \text{ W}$

Symbol	Test Conditions	Maximum Ratings	
$V_{DSS}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$	200	V
$V_{DGR}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$ ; $R_{GS} = 1 \text{ M}\Omega$	200	V
$V_{GS}$	Continuous	$\pm 20$	V
$V_{GSM}$	Transient	$\pm 30$	V
$I_{D25}$	$T_c = 25^\circ\text{C}$	25	A
$I_{DM}$	$T_c = 25^\circ\text{C}$ , pulse width limited by $T_{JM}$	150	A
$I_{AR}$	$T_c = 25^\circ\text{C}$	25	A
$E_{AR}$	$T_c = 25^\circ\text{C}$	20	mJ
$dv/dt$	$I_S \leq I_{DM}$ , $di/dt \leq 100 \text{ A}/\mu\text{s}$ , $V_{DD} \leq V_{DSS}$ , $T_J \leq 150^\circ\text{C}$ , $R_G = 0.2 \Omega$	5	V/ns
	$I_S = 0$	>200	V/ns
$P_{DC}$		590	W
$P_{DHS}$	$T_c = 25^\circ\text{C}$ Derate $1.9 \text{ W}/^\circ\text{C}$ above $25^\circ\text{C}$	284	W
$P_{DAMB}$	$T_c = 25^\circ\text{C}$	3.0	W
$R_{thJC}$		0.25	C/W
$R_{thJHS}$		0.53	C/W



#### Features

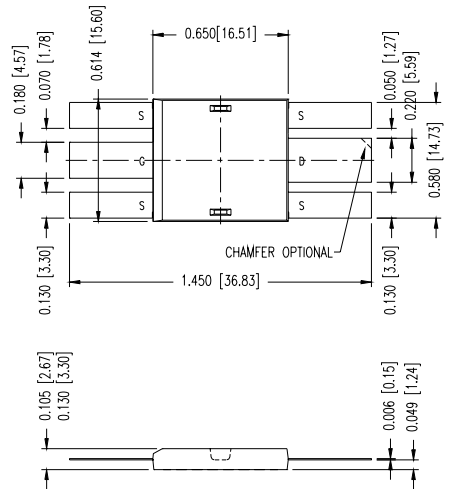
- Isolated Substrate
  - high isolation voltage (>2500V)
  - excellent thermal transfer
  - Increased temperature and power cycling capability
- IXYS advanced low  $Q_g$  process
- Low gate charge and capacitances
  - easier to drive
  - faster switching
- Low  $R_{DS(on)}$
- Very low insertion inductance (<2nH)
- No beryllium oxide (BeO) or other hazardous materials

#### Advantages

- Optimized for RF and high speed switching at frequencies to 100MHz
- Easy to mount—no insulators needed
- High power density

Symbol	Test Conditions	Characteristic Values		
		$T_J = 25^\circ\text{C}$ unless otherwise specified		
		min.	typ.	max.
$V_{DSS}$	$V_{GS} = 0 \text{ V}$ , $I_D = 3 \text{ ma}$	200		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 4 \text{ ma}$	2.5		5.5 V
$I_{GSS}$	$V_{GS} = \pm 20 \text{ V}_{DC}$ , $V_{DS} = 0$			$\pm 100 \text{ nA}$
$I_{DSS}$	$V_{DS} = 0.8 V_{DSS}$ , $T_J = 25^\circ\text{C}$ $V_{GS} = 0$ , $T_J = 125^\circ\text{C}$			50 $\mu\text{A}$
				1 mA
$R_{DS(on)}$	$V_{GS} = 15 \text{ V}$ , $I_D = 0.5 I_{D25}$ Pulse test, $t \leq 300 \mu\text{s}$ , duty cycle $d \leq 2\%$			.08 $\Omega$
$g_{fs}$	$V_{DS} = 15 \text{ V}$ , $I_D = 0.5 I_{D25}$ , pulse test		18	S
$T_J$		-55		+175 $^\circ\text{C}$
$T_{JM}$			175	$^\circ\text{C}$
$T_{stg}$		-55		+175 $^\circ\text{C}$
$T_L$	1.6mm(0.063 in) from case for 10 s		300	$^\circ\text{C}$
<b>Weight</b>			2	g

Symbol	Test Conditions	Characteristic Values		
		(T <sub>J</sub> = 25°C unless otherwise specified)		
		min.	typ.	max.
<b>R<sub>G</sub></b>			0.3	Ω
<b>C<sub>iss</sub></b>			2500	pF
<b>C<sub>oss</sub></b>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 0.8 V <sub>DSS(max)</sub> , f = 1 MHz		250	pF
<b>C<sub>rss</sub></b>			50	pF
<b>C<sub>stray</sub></b>	Back Metal to any Pin		21	pF
<b>T<sub>d(on)</sub></b>			5	ns
<b>T<sub>on</sub></b>	V <sub>GS</sub> = 15 V, V <sub>DS</sub> = 0.8 V <sub>DSS</sub> I <sub>D</sub> = 0.5 I <sub>DM</sub>		5	ns
<b>T<sub>d(off)</sub></b>	R <sub>G</sub> = 0.2 Ω (External)		8	ns
<b>T<sub>off</sub></b>			8	ns
<b>Q<sub>g(on)</sub></b>			50	nC
<b>Q<sub>gs</sub></b>	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 0.5 V <sub>DSS</sub> I <sub>D</sub> = 0.5 I <sub>D25</sub>		20	nC
<b>Q<sub>gd</sub></b>			30	nC



Symbol	Test Conditions	Characteristic Values		
		(T <sub>J</sub> = 25°C unless otherwise specified)		
		min.	typ.	max.
<b>I<sub>S</sub></b>	V <sub>GS</sub> = 0 V			25 A
<b>I<sub>SM</sub></b>	Repetitive; pulse width limited by T <sub>JM</sub>			150 A
<b>V<sub>SD</sub></b>	I <sub>F</sub> = I <sub>S</sub> , V <sub>GS</sub> = 0 V, Pulse test, t ≤ 300 μs, duty cycle ≤ 2%			2.0 V
<b>T<sub>rr</sub></b>			300	ns

For detailed device mounting and installation instructions, see the “*DE-Series MOSFET Mounting Instructions*” technical note on IXYS RF’s web site at [www.ixysrf.com/Technical\\_Support/App\\_notes.html](http://www.ixysrf.com/Technical_Support/App_notes.html)

IXYS RF reserves the right to change limits, test conditions and dimensions.

IXYS RF MOSFETS are covered by one or more of the following U.S. patents:

- |           |           |           |           |           |           |
|-----------|-----------|-----------|-----------|-----------|-----------|
| 4,835,592 | 4,850,072 | 4,881,106 | 4,891,686 | 4,931,844 | 5,017,508 |
| 5,034,796 | 5,049,961 | 5,063,307 | 5,187,117 | 5,237,481 | 5,486,715 |
| 5,381,025 | 5,640,045 |           |           |           |           |

**201N25A DE-SERIES SPICE Model**

The DE-SERIES SPICE Model is illustrated in Figure 1. The model is an expansion of the SPICE level 3 MOSFET model. It includes the stray inductive terms  $L_G$ ,  $L_S$  and  $L_D$ .  $R_d$  is the  $R_{DS(ON)}$  of the device,  $R_{ds}$  is the resistive leakage term. The output capacitance,  $C_{OSS}$ , and reverse transfer capacitance,  $C_{RSS}$  are modeled with reversed biased diodes. This provides a varactor type response necessary for a high power device model. The turn on delay and the turn off delay are adjusted via  $R_{on}$  and  $R_{off}$ .

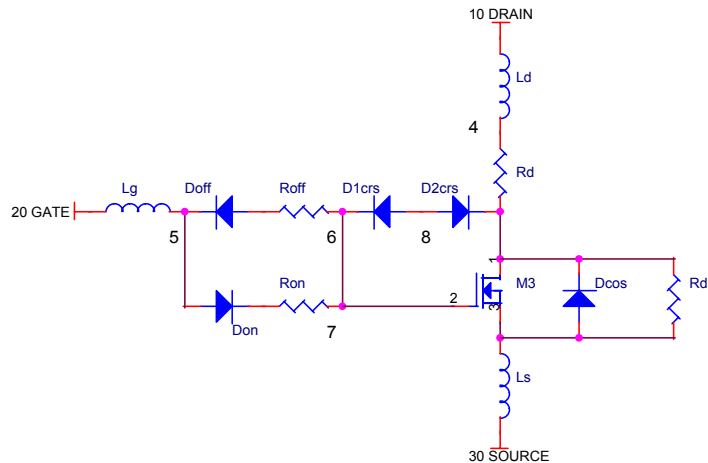


Figure 1 DE-SERIES SPICE Model

This SPICE model may be downloaded as a text file from the DEI web site at [www.directedenergy.com/spice.htm](http://www.directedenergy.com/spice.htm)

Net List:

```
*****
*SYM=POWMOSN
.SUBCKT 201N25A 10 20 30
* TERMINALS: D G S
* 200 Volt 25 Amp .08 ohm N-Channel Power MOSFET
M1 1 2 3 3 DMOS L=1U W=1U
RON 5 6 1.5
DON 6 2 D1
ROF 5 7 .2
DOF 2 7 D1
D1CRS 2 8 D2
D2CRS 1 8 D2
CGS 2 3 2.5N
RD 4 1 .08
DCOS 3 1 D3
RDS 1 3 5.0MEG
LS 3 30 .1N
LD 10 4 1N
LG 20 5 1N
.MODEL DMOS NMOS (LEVEL=3 VTO=3.0 KP=25.0)
.MODEL D1 D (IS=.5F CJO=1P BV=100 M=.5 VJ=.6 TT=1N)
.MODEL D2 D (IS=.5F CJO=1100P BV=500 M=.5 VJ=.6 TT=1N RS=10M)
.MODEL D3 D (IS=.5F CJO=300P BV=500 M=.3 VJ=.4 TT=400N RS=10M)
.ENDS
```

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